

Material Composition Specification

SMB Case



Device average mass 92 mg
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.83%	0.76	Si	7440-21-3	0.83%	0.76	8,262
leadframe	copper	37%	34.04	Cu	7440-50-8	37%	34.04	370,032
die attach	high temperature solder paste	2.45%	2.25	Pb	7439-92-1	2.26%	2.081	22,622
				Sn	7440-31-5	0.12%	0.113	1,228
				Ag	7440-22-4	0.06%	0.056	609
encapsulation*	EMC	58.96%	54.23	silica	7631-86-9	40.09%	36.88	400,904
				epoxy resin	29690-82-2	11.79%	10.85	117,945
				phenol resin	9003-35-4	5.89%	5.42	58,918
				Sb ₂ O ₃	1309-64-4	0.59%	0.542	5,892
				Br	7726-95-6	0.59%	0.542	5,892
	EMC GREEN	58.96%	54.23	silica (fused)	60676-86-0	45.4%	41.76	453,953
				epoxy resin	29690-82-2	5.9%	5.423	58,951
				phenol resin	9003-35-4	5.72%	5.26	57,179
				carbon black	1333-86-4	0.18%	0.163	1,772
				metal hydroxide	1309-42-8	1.77%	1.628	17,697
plating**	tin/lead process	0.77%	0.71	Sn	7440-31-5	0.62%	0.566	6,153
				Pb	7439-92-1	0.15%	0.142	1,544
	matte tin	0.77%	0.71	Sn	7440-31-5	0.77%	0.708	7,696

*EMC GREEN molding compound is Halogen-Free.

**For Lead Free plating, add suffix "LEAD FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

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